

Notice of References Cited	Application/Control No. 10/560,073		Applicant(s)/Patent Under Reexamination MASUKO ET AL.	
	Examiner ANISH DESAI		Art Unit 1794	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-2002/0048726 A1	04-2002	Kikkawa et al.	430/283.1
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*	C	US-5,690,837	11-1997	Nakaso et al.	216/17
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	K	US-			
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	M	US-			

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Fujii Shinjiro, "Adhesive for Die Bonding and Preparation of Semiconductor Device", Machine translation of JP 2000-104040, pages 1-13, 04/11/2000.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.